



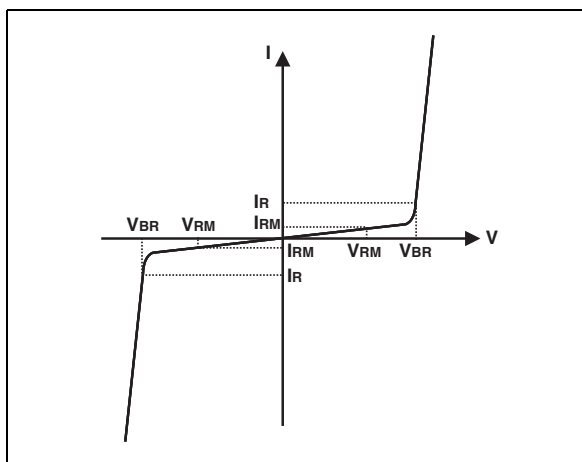
## EMIF04-VID01F2

**Table 2: Absolute Ratings** (limiting values)

Symbol	Parameter and test conditions	Value	Unit
$T_j$	Maximum junction temperature	125	°C
$T_{op}$	Operating temperature range	- 40 to + 85	°C
$T_{stg}$	Storage temperature range	- 55 to + 150	°C

**Table 3: Electrical Characteristics** ( $T_{amb} = 25^\circ\text{C}$ )

Symbol	Parameter
$V_{BR}$	Breakdown voltage
$I_{RM}$	Leakage current @ $V_{RM}$
$V_{RM}$	Stand-off voltage
$R$	Series resistance between Input & Output
$C_{line}$	Input capacitance per line



Symbol	Test conditions	Min.	Typ.	Max.	Unit
$V_{BR}$	$I_R = 1\text{mA}$	6	8	10	V
$I_{RM}$	$V_{RM} = 3\text{V per line}$			500	nA
$R$	$I = 10\text{mA}$	80	100	120	$\Omega$
$C_{line}$	$V_R = 3\text{V DC}$ $1\text{MHz}$ $V_{OSC} = 30\text{mV}$		16	19	pF

Figure 3: S21 (dB) attenuation measurement

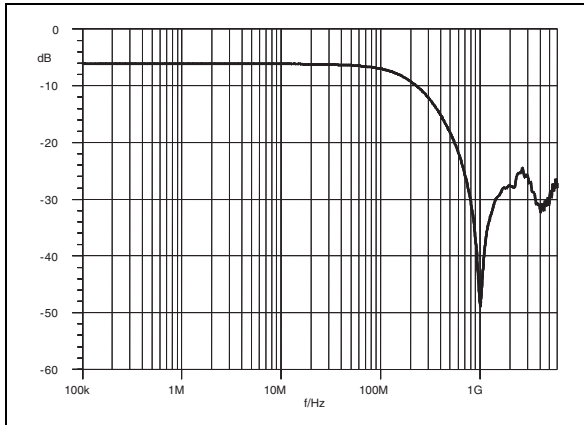


Figure 4: Analog crosstalk measurement

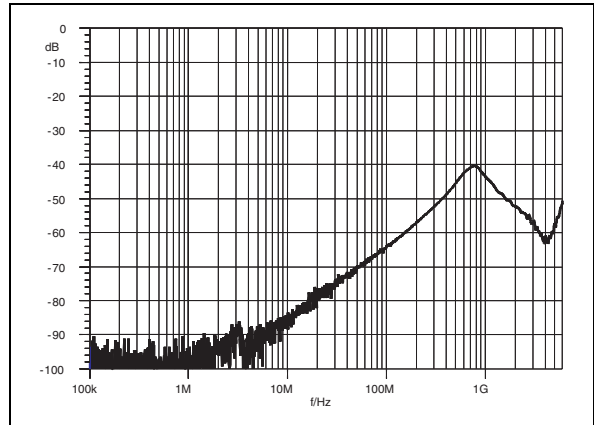


Figure 5: ESD response to IEC61000-4-2 (+15kV air discharge) on one input V(in) and on one output (Vout)

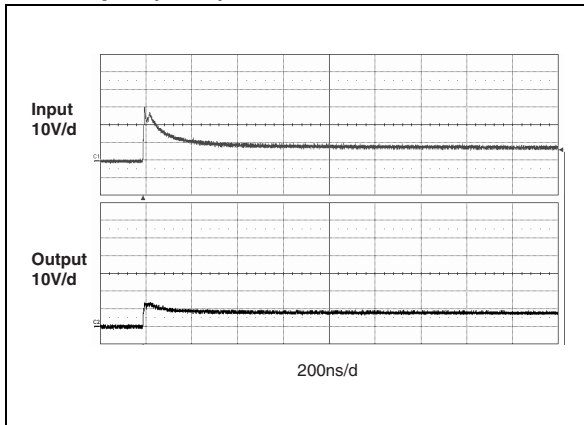


Figure 6: ESD response to IEC61000-4-2 (-15kV air discharge) on one input V(in) and on one output (Vout)

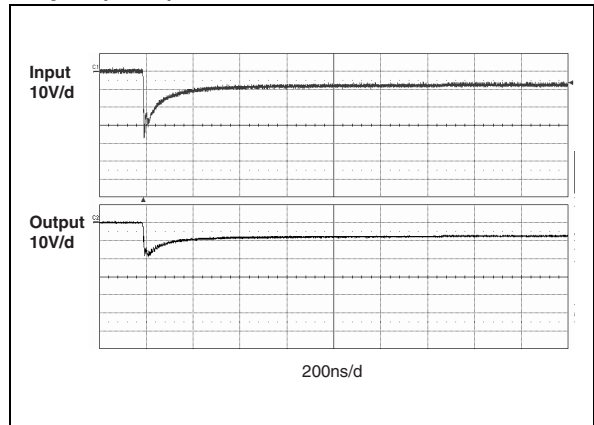


Figure 7: Junction capacitance versus reverse voltage applied (typical values)

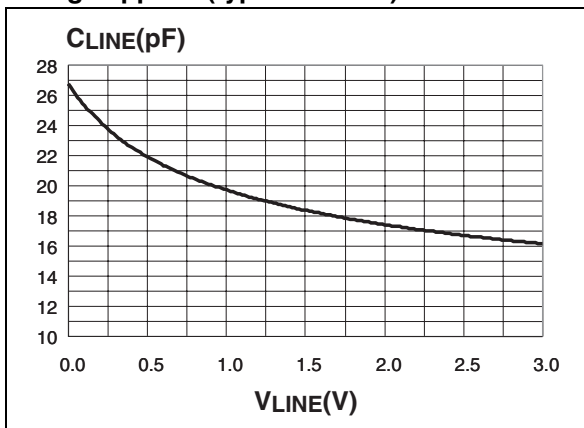


Figure 8: Ordering Information Scheme

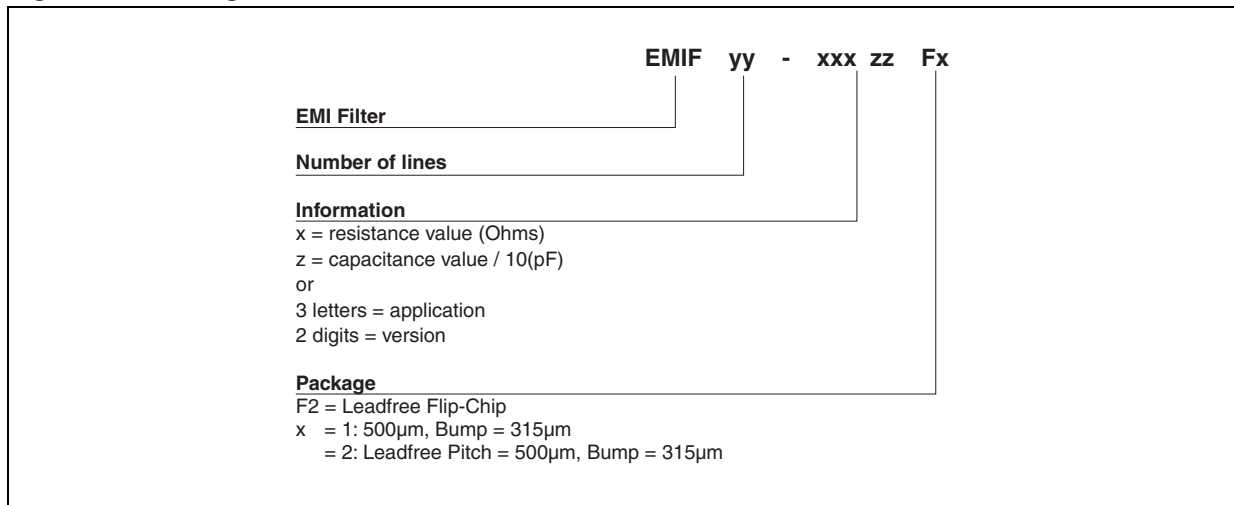


Figure 9: FLIP-CHIP Package Mechanical Data

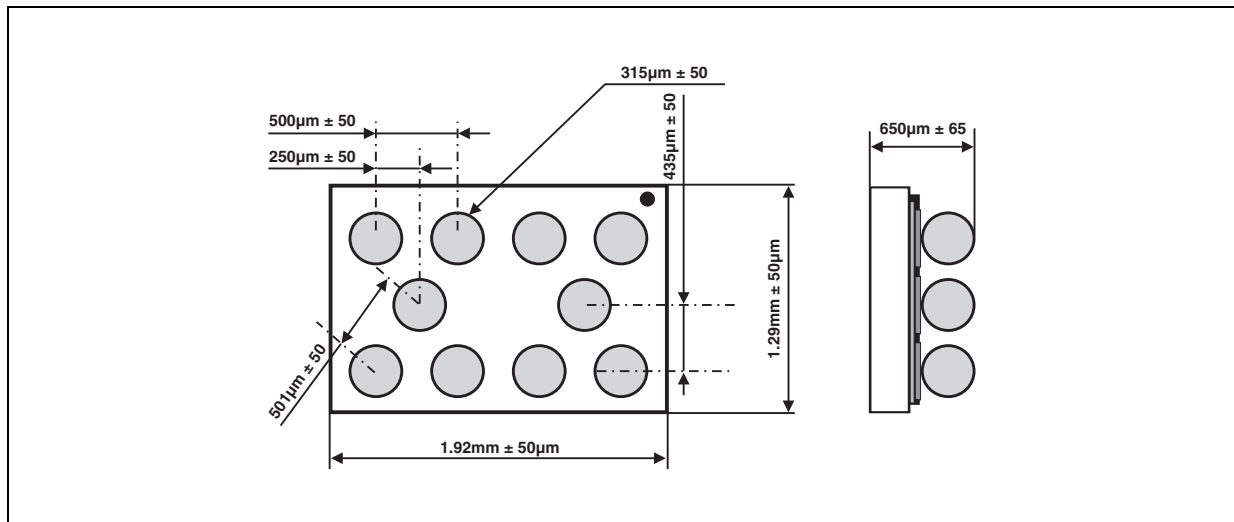


Figure 10: Foot Print Recommendations

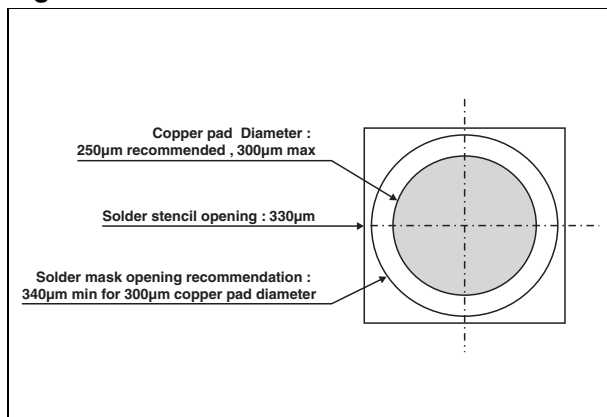


Figure 11: Marking

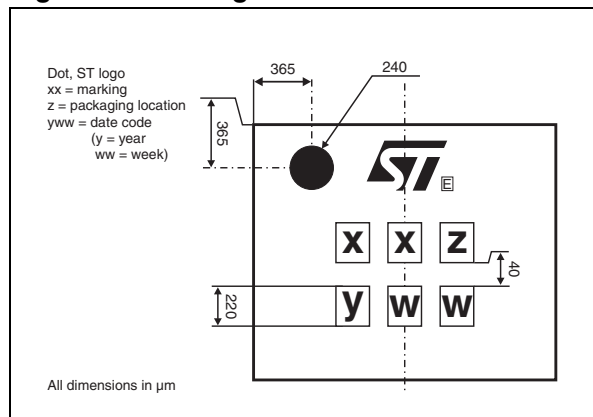


Figure 12: FLIP-CHIP Tape and Reel Specification

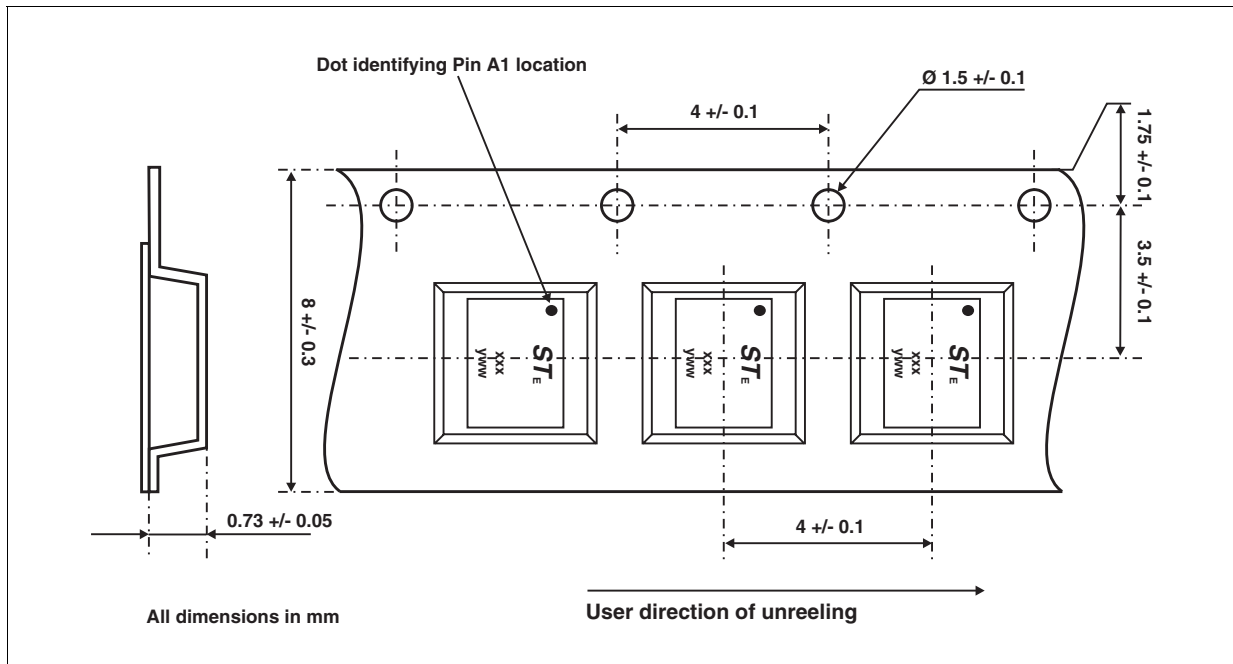


Table 4: Ordering Information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF04-VID01F2	GU	Flip-Chip	3.6 mg	5000	Tape & reel 7"

**Note:** More packing informations are available in the application note  
 AN1235: "Flip-Chip: Package description and recommendations for use"  
 AN1751: "EMI Filters: Recommendations and measurements"

Table 5: Revision History

Date	Revision	Description of Changes
15-Feb-2005	1	First issue.

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